

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
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EPAS ID: PAT7765763

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the ASSIGNEE(S) previously recorded on Reel 046381 Frame 0808. Assignor(s) hereby confirms the ASSIGNEE IS SAMSUNG ELECTRONICS CO., LTD. AND DONG WON SHIN.
CONVEYING PARTY DATA	
Name	Execution Date
KYUNG-MOO CHOI	07/10/2018
DONG WON SHIN	07/09/2018
RECEIVING PARTY DATA	
Name:	SAMSUNG ELECTRONICS CO., LTD.
Street Address:	129, SAMSUNG-RO, YEONGTONG-GU, GYEONGGI-DO
City:	SUWON-SI
State/Country:	KOREA, REPUBLIC OF
Postal Code:	16677
Name:	DONG WON SHIN
Street Address:	201-702, 23, MUNHWA-RO, NAM-GU
City:	INCHEON
State/Country:	KOREA, REPUBLIC OF
Postal Code:	22241
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16038348
CORRESPONDENCE DATA	
Fax Number:	(202)293-7860
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	2022937060
Email:	aquiroa@sughrue.com, sughrue@sughrue.com
Correspondent Name:	SUGHRUE MION, PLLC
Address Line 1:	2000 PENNSYLVANIA AVENUE NW
Address Line 2:	SUITE 900
Address Line 4:	WASHINGTON, D.C. 20006
ATTORNEY DOCKET NUMBER:	Q240795
NAME OF SUBMITTER:	ARI QUIROA

SIGNATURE:	/AAQ-TEAMS/
DATE SIGNED:	01/27/2023
Total Attachments: 8 source=Q240795MarkedUpNOR#page1.tif source=Q240795MarkedUpNOR#page2.tif source=Q240795MarkedUpNOR#page3.tif source=Q240795NoticeofRecordation#page1.tif source=Q240795NoticeofRecordation#page2.tif source=Q240795NoticeofRecordation#page3.tif source=Q240795AssignmentwithDeclarationexecuted#page1.tif source=Q240795AssignmentwithDeclarationexecuted#page2.tif	

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PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
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EPAS ID: PAT5055560

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
KYUNG-MOO CHOI	07/10/2018
DONG WON SHIN	07/09/2018
RECEIVING PARTY DATA	
Name:	SAMSUNG ELECTRONICS CO., LTD.
Street Address:	129, SAMSUNG-RO, YEONGTONG-GU, GYEONGGI-DO
City:	SUWON-SI
State/Country:	KOREA, REPUBLIC OF
Postal Code:	16677
Name:	DONG WON SHIN
Street Address:	201-702, 23, MUNHWA-RO, NAM-GU
City:	INCHEON
State/Country:	KOREA, REPUBLIC OF
Postal Code:	22241
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16038348
CORRESPONDENCE DATA	
Fax Number:	(202)293-7660
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	202-293-7060
Email:	tyarborsugh@sughrue.com, sughrue@sughrue.com
Correspondent Name:	SUGHRUE MION, PLLC
Address Line 1:	2100 PENNSYLVANIA AVENUE, N.W.
Address Line 2:	SUITE 800
Address Line 4:	WASHINGTON, D.C. 20037
ATTORNEY DOCKET NUMBER:	O240795
NAME OF SUBMITTER:	TODD YARBOROUGH, TEAMS DEPT
SIGNATURE:	/Todd Yarbrough/

ASSIGNMENT WITH DECLARATION FOR UTILITY OR DESIGN PATENT APPLICATION (37 CFR 1.63)

Whereas, We, the undersigned inventors hereinafter called assignors, have invented certain improvements described in the application identified below; and

Whereas, SAMSUNG ELECTRONICS CO., LTD. of 129, Samsung-ro, Yeongtong-gu, Suwon-si, Gyeonggi-do, 16677, Republic of Korea and Dong Won SHIN of 201-702, 23, Munhwa-ro, Nam-gu, Incheon, 22241, Republic of Korea, (assignee), desires to acquire the entire right, title, and interest in the application and invention, and to any United States patents to be obtained therefor;

Now therefore, for valuable consideration, receipt whereof is hereby acknowledged,

We, the above named assignors, hereby sell, assign and transfer to the above named assignee, its successors and assigns, the entire right, title and interest in the application and the invention disclosed therein for the United States of America and all other countries, including all divisions, and continuations thereof, and all Letters Patent of the United States that may be granted thereon, and all reissues thereof, and including rights of priority under the International Convention of Paris (1883) as amended, the laws of all foreign countries, and the laws of the United States including the right to claim priority under 35 USC 119 and the right to sue for past damages, and we request the Director of the U.S. Patent and Trademark Office to issue any Letters Patent granted upon the invention set forth in the application to the assignee, its successors and assigns; and we hereby agree that the assignee may apply for foreign Letters Patent on the invention and we will execute without further consideration all papers deemed necessary by the assignee in connection with the United States and foreign applications when called upon to do so by the assignee.

(Legalization not required for recording but is prima facie evidence of execution under 35 USC 261)

As the below named inventor, I hereby declare that:

This assignment with declaration is directed to: The attached application, or
 United States Application or PCT International Application Number _____ filed on _____.

The application is entitled:

BONDING INTERPOSER AND INTEGRATED CIRCUIT CHIP, AND ULTRASOUND PROBE USING THE SAME

The above identified application was made or was authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I have reviewed and understand the contents of the application for which this assignment with declaration is being submitted.

I am aware of the duty to disclose to the Office all information known to me to be material to patentability as defined in 37 CFR 1.56.

I hereby acknowledge that any willful false statement made in this assignment with declaration is punishable under 18 USC 1001 by fine or imprisonment of not more than five (5) years, or both.

NAME OF SOLE OR FIRST INVENTOR:	
Given Name (first and middle [if any]) Kyung-moo	Family Name or Surname CHOI
Inventor's signature <i>Kyungmoo Choi</i>	Date 2018. 2. 10
Residence: Yongin-si, Republic of Korea	
Mailing Address: 101-501, 30, Seogeunae-ro 16beon-gil, Giheung-gu, Yongin-si, Gyeonggi-do, Republic of Korea	

NAME OF SECOND INVENTOR:	
Given Name (first and middle [if any]) Dong Won	Family Name or Surname SHIN
Inventor's signature <i>Dong Won Shin</i>	Date 2018. 1. 9
Residence: Incheon, Republic of Korea	
Mailing Address: 201-702, 23, Munhwa-ro, Nam-gu, Incheon, Republic of Korea	